

AMENDMENTS TO THE CLAIMS

1-8. (Cancelled)

9. (Currently Amended) The apparatus of claim ~~8-15~~ wherein the workpiece support is configured to also move the workpiece vertically between a processing position and a receive wafer position.

10. (Currently Amended) The apparatus of claim ~~8-15~~ wherein the drive unit is operatively coupled to the workpiece support to rotate the workpiece support about a rotation axis.

11. (Currently Amended) The tool of claim ~~8-15~~ wherein the processing vessel is configured to receive an electrochemical processing liquid.

12. (Currently Amended) The apparatus of claim ~~8-15~~ wherein the processing vessel extends below the deck.

13. (Currently Amended) The apparatus of claim ~~8-15~~ wherein the workpiece support is configured to carry the workpiece in contact with a processing liquid.

14. (Currently Amended) The apparatus of claim ~~8-15~~ wherein the workpiece support includes at least one contact assembly having at least one electrical contact positioned to make contact with the workpiece.

15. (Currently Amended) ~~The apparatus of claim 8~~An apparatus for processing planar semiconductor workpieces, comprising:
a semiconductor process machine having a deck;

a processing vessel in the semiconductor process machine, the processing vessel being configured to receive at least one processing liquid;
a workpiece support having a base attached to the deck of the semiconductor process machine and a moveable workpiece holder configured to carry a planar semiconductor workpiece at least proximate to the processing vessel in a processing plane;
a drive unit operatively coupled to the workpiece holder to rotate the planar semiconductor workpiece about an axis normal to the processing plane; and
wherein the base of the workpiece support is at or above the deck, and wherein the workpiece support includes at least one electrode and at least one sheath positioned to seal against a surface of the workpiece.

16. (Currently Amended) ~~The apparatus of claim 8~~An apparatus for processing planar semiconductor workpieces, comprising:

a semiconductor process machine having a deck;
a processing vessel in the semiconductor process machine, the processing vessel being configured to receive at least one processing liquid;
a workpiece support having a base attached to the deck of the semiconductor process machine and a moveable workpiece holder configured to carry a planar semiconductor workpiece at least proximate to the processing vessel in a processing plane;
a drive unit operatively coupled to the workpiece holder to rotate the planar semiconductor workpiece about an axis normal to the processing plane; and
wherein the base of the workpiece support is at or above the deck, and wherein the deck includes an aperture in which the processing vessel is received.

17. (New) The apparatus of claim 16 wherein the workpiece support is configured to also move the workpiece vertically between a processing position and a receive wafer position.

18. (New) The apparatus of claim 16 wherein the drive unit is operatively coupled to the workpiece support to rotate the workpiece support about a rotation axis.

19. (New) The tool of claim 16 wherein the processing vessel is configured to receive an electrochemical processing liquid.

20. (New) The apparatus of claim 16 wherein the processing vessel extends below the deck.

21. (New) The apparatus of claim 16 wherein the workpiece support is configured to carry the workpiece in contact with a processing liquid.

22. (New) The apparatus of claim 16 wherein the workpiece support includes at least one contact assembly having at least one electrical contact positioned to make contact with the workpiece.